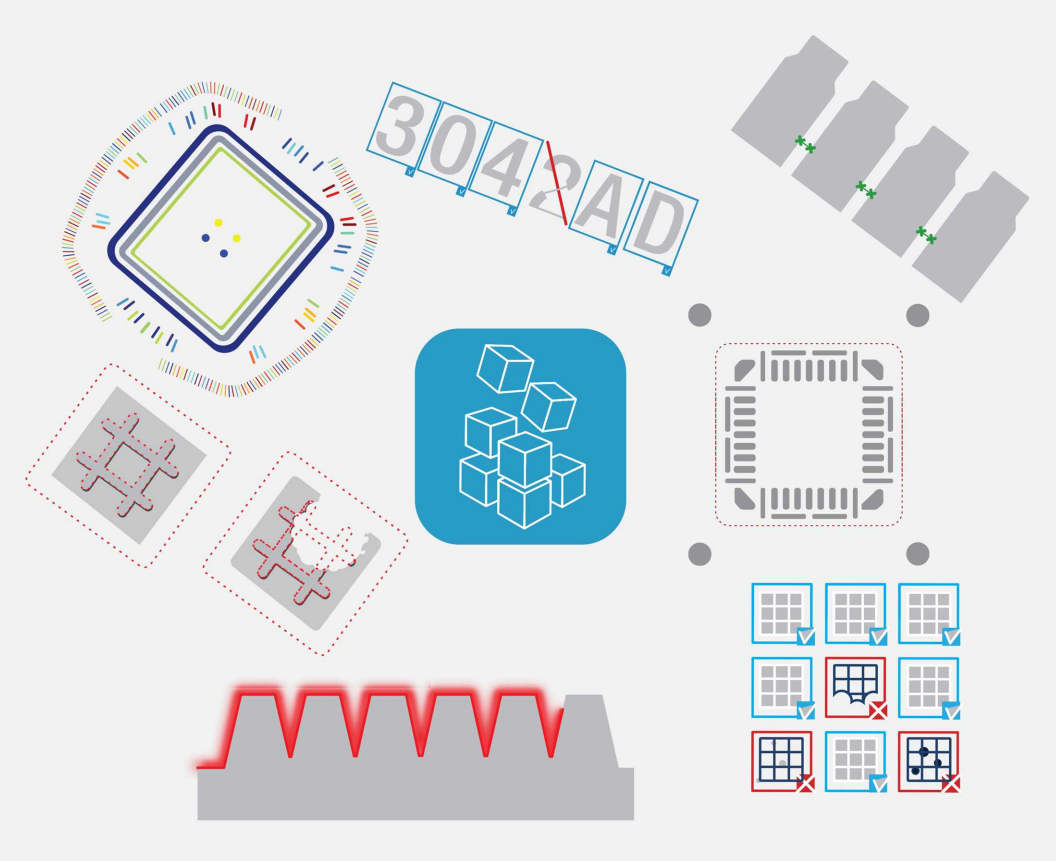


# Open eVision

Inspecting Pads Using Regions



This documentation is provided with **Open eVision 24.02.0** (doc build **1198**).  
[www.euresys.com](http://www.euresys.com)

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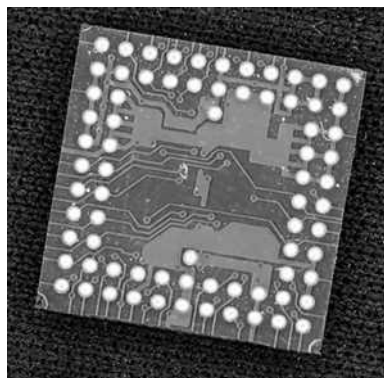
# 1. Inspecting Pads Using Regions

See also: [Arbitrary-Shaped ROI \(ERegion\)](#) / [code snippets: ERegion](#)

The code of this application is available in the GGeRegion sample installed with **Open eVision**.

## Application objective

This application demonstrates how to use regions to inspect the pads on the underside of a non-aligned electronic chip package.



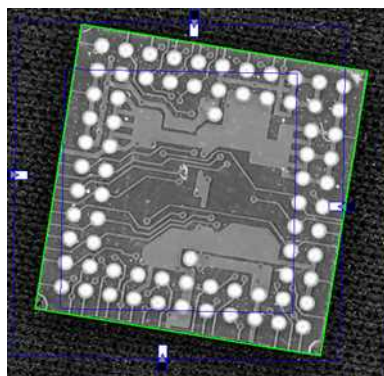
### NOTE

To run this program, you need the EasyObject and EasyGauge licenses.

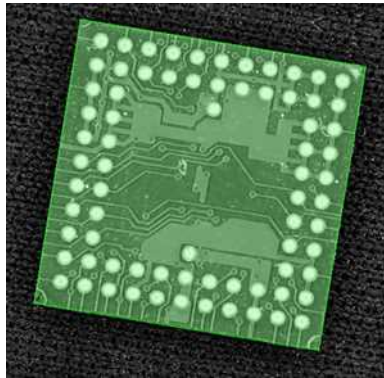
## Processing

To do this, we will use EasyGauge to detect the position of the package, then perform an EasyObject segmentation on the detected position:

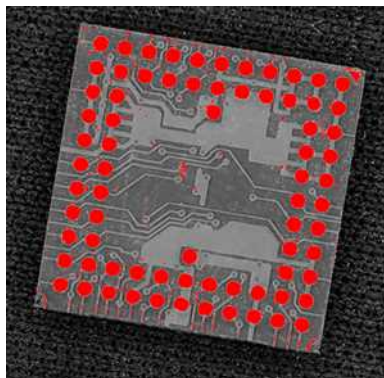
1. Use [ERectangleGauge](#) from the **EasyGauge** library to detect the package and its position.



2. Use the `ERectangleRegion::ERectangleRegion(ERectangle&)` constructor with the `ERectangle` returned by `ERectangleGauge` to create an `ERegion`.



3. Use the `EImageEncoder::Encode(EImage&, ERegion&, ECodedImage&)` method from the `EasyObject` library to perform the blob detection within the region.



4. Filter the blobs using `EObjectSelection`.
5. Perform any required measurement and check.

